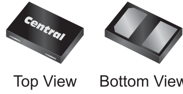
Material Composition Specification
SOD-882 Case



Device average mass . . . . **1.1 mg**
Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	1.64%	0.018	Si	7440-21-3	1.64%	0.018	16,364
bond wire	gold	0.36%	0.004	Au	7440-57-5	0.36%	0.004	3,636
leadframe	Cu alloy	21.31%	0.2344	Cu	7440-50-8	21.18%	0.233	211,818
				Cr	7440-47-3	0.05%	0.0005	455
				Sn	7440-31-5	0.05%	0.0005	455
				Zn	7440-66-6	0.04%	0.0004	364
die attach	silver epoxy	0.27%	0.003	Ag	7440-22-4	0.18%	0.002	1,818
				epoxy resin	Proprietary	0.09%	0.001	909
encapsulation*	EMC GREEN	75.24%	0.8276	silica (fused)	60676-86-0	58.27%	0.641	582,727
				epoxy resin	29690-82-2	7.39%	0.0813	73,909
				phenol resin	9003-35-4	7.39%	0.0813	73,909
				carbon black	1333-86-4	0.18%	0.002	1,818
				metal hydroxide	1309-42-8	2.0%	0.022	20,000
plating	matte tin	1.18%	0.013	Sn	7440-31-5	1.18%	0.013	11,818

*EMC GREEN molding compound is Halogen-Free.

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.